

Electronic Acknowledgement Receipt

EFS ID:	1087145
Application Number:	10688689
Confirmation Number:	2379
Title of Invention:	METHOD AND STRUCTURE FOR SELF HEALING CRACKS IN UNDERFILL MATERIAL BETWEEN AN I/C CHIP AND A SUBSTRATE BONDED TOGETHER WITH SOLDER BALLS
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Change of Address	Change_of_Address_6_21_06.pdf	22789	no	1

Warnings:**Information:****Total Files Size (in bytes):**

22789

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If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.